



IEC 62899-402-8

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# INTERNATIONAL STANDARD

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**Printed electronics -  
Part 402-8: Printability - Measurement of qualities - Shape pattern dimension**

## CONTENTS

|  |    |
|--|----|
| FOREWORD .....   | 3  |
| INTRODUCTION .....   | 5  |
| 1 Scope .....  | 6  |
| 2 Normative references .....   | 6  |
| 3 Terms and definitions .....  | 6  |
| 4 Atmospheric conditions for evaluation and conditioning .....   | 7  |
| 5 Measuring methods and instruments .....  | 7  |
| 5.1 Measuring instrument .....   | 7  |
| 5.2 Preparation of imaging (specimen).....   | 7  |
| 5.3 Overview of measuring method .....   | 8  |
| 5.4 Measuring method for basic shape patterns .....  | 8  |
| 5.4.1 Measuring method for a circle/a part of circle pattern.....  | 8  |
| 5.4.2 Measuring method for square or rectangle pattern .....   | 11 |
| 5.4.3 Measuring method for line pattern .....  | 14 |
| 5.5 Measuring methods for a combination of basic shape patterns.....   | 14 |
| 6 Report of results .....  | 14 |
| 6.1 Measurement identification information .....   | 14 |
| 6.2 Atmospheric conditions .....   | 14 |
| 6.3 Instrument system and its specification .....  | 14 |
| 6.4 Information of specimen.....   | 15 |
| 6.5 Results .....  | 15 |
| Annex A (informative) Examples and guidelines for finding the centre of the circle pattern.....                  | 16 |
| A.1 Examples for finding the centre of the circle pattern.....   | 16 |
| A.1.1 Using a rectangle passing the outmost edges .....  | 16 |
| A.1.2 Using two or more lines passing any two points of edge .....   | 17 |
| A.2 Guidelines for finding the centre of an arc (a part of a circle) or a circle pattern with large defects..... | 18 |
| A.2.1 Examples of a part of circle and a circle pattern with large defects .....                                 | 18 |
| A.2.2 Method to find centre.....   | 18 |
| Annex B (informative) Calculation of dimensions of a circle pattern .....  | 21 |
| B.1 Calculation of variations of radius and diameter .....   | 21 |
| B.2 Calculation of variations of radius and diameter relative to designed dimension .....                        | 22 |
| Annex C (informative) Calculation of dimensions of a rectangle pattern .....                                     | 24 |
| Annex D (informative) Examples of measuring method for a combination of basic shape patterns.....                | 26 |
| D.1 Measuring method for a combination of circle and lines .....   | 26 |
| D.1.1 Examples of circle and lines .....   | 26 |
| D.1.2 Measuring method .....   | 26 |
| D.2 Measuring method for a combination of rectangle and lines .....  | 26 |
| D.2.1 Examples of a combination of rectangle and lines.....  | 26 |
| D.2.2 Measurement method .....   | 27 |
| D.3 Measuring method for angle bracket .....   | 27 |
| D.3.1 Examples of angle bracket.....   | 27 |
| D.3.2 Measuring method for angle bracket .....   | 28 |

|  |    |
|--|----|
| Bibliography.....  | 29 |
| Figure 1 – Original image and a circle drawn .....   | 8  |
| Figure 2 – Recognized edges of circle pattern and estimated centre of the circle .....   | 10 |
| Figure 3 – Edges of square image and a rectangle drawn .....   | 11 |
| Figure 4 – Identified edges and reference sides of the rectangle.....  | 13 |
| Figure A.1 – Method to find the centre of a circle pattern using vertical and horizontal lines passing the outmost edges ..... | 16 |
| Figure A.2 – Method to find the centre of a circle pattern using a rectangle passing the outmost edges .....                   | 17 |
| Figure A.3 – Estimation of the centre of a circle pattern using multiple sets of rectangles.....                               | 17 |
| Figure A.4 – Method to find the centre of a circle pattern using two or more lines passing two points of the edge.....         | 18 |
| Figure A.5 – Example of a part of circle and circle patterns with large defects .....  | 18 |
| Figure A.6 – Estimated centre of a circle pattern including defect part .....  | 19 |
| Figure A.7 – Estimated centre of a circle pattern excluding defect part .....  | 20 |
| Figure B.1 – Definition of position of pixel of edge of a circle in polar coordinate .....                                     | 21 |
| Figure B.2 – Definition of position of pixel of edge of a part of circle in polar coordinate .....                             | 21 |
| Figure B.3 – Variations of radius of the circle pattern.....   | 22 |
| Figure B.4 – Variations of diameter of the circle pattern.....   | 22 |
| Figure B.5 – Variations of diameter of the circle pattern and original diameter of a circle.....                               | 23 |
| Figure B.6 – Variation of diameter relative to the original dimension .....  | 23 |
| Figure C.1 – Definition of reference vertical and horizontal lines to calculate dimensions of rectangle .....                  | 24 |
| Figure C.2 – Variations of lengths and widths of the rectangle .....   | 25 |
| Figure D.1 – Example of combination of circle and lines .....  | 26 |
| Figure D.2 – Measurement method for pattern dimensions of a combination of circle and line.....                                | 26 |
| Figure D.3 – Combination of rectangle and lines .....  | 27 |
| Figure D.4 – Measurement method for pattern dimensions of combination of rectangle and lines .....                             | 27 |
| Figure D.5 – Example of angle bracket pattern in circuit (a) and enlarged picture of angle bracket pattern (b).....            | 28 |
| Figure D.6 – Measurement method for angle bracket pattern .....  | 28 |
| Table 1 – Example of reporting items .....   | 15 |

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**Printed electronics -  
Part 402-8: Printability - Measurement of qualities - Shape pattern  
dimension**

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The text of this International Standard is based on the following documents:

| Draft       | Report on voting |
|-------------|------------------|
| 119/532/CDV | 119/563A/RVC     |

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/publications](http://www.iec.ch/publications).

A list of all parts in the IEC 62899 series, published under the general title *Printed electronics*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under [webstore.iec.ch](http://webstore.iec.ch) in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn, or
- revised.

## INTRODUCTION

This document specifies the measurement of dimensions of the shape patterns in printed electronics. The shape patterns include various patterns with shapes such as circle, ellipse, square, rectangle, etc., as well as a combination of two or more of these, which are commonly used as parts of printed electronics devices. Various shape patterns constitute printed electronics devices, and consequently, the printability of patterns including dimension, gain, loss and distortion affects device performance. Therefore, it is important to measure the dimensions of shape patterns from the viewpoint of printability.

Some parts of pattern measurement have been specified for line pattern width, edge, and voids in IEC 62899-402-1, IEC 62899-402-2, and IEC 62899-402-3, respectively. The IEC 62899-403 series includes basic patterns for evaluation of printing machine, basic patterns for plating, etc., and moreover, IEC 62899-301-2 deals with the measurement of plate master pattern dimension. However, there is no standard for the measurement of printed patterns with general shapes. Therefore, this document is used to measure the dimensions of printed patterns as the result of the pattern design of the IEC 62899-403 series and plate patterns of IEC 62899-301-2 as well as to compare the dimensions of printed patterns with the pattern design for evaluating the printability.

This document includes two methods for the measurement of dimensions of the shape patterns: The first one is to simply specify the dimension of the shape and compare with the original design, and the second one is to specify the dimension as well as to quantify the related attributes such as variation of dimension. For more accurate measurement of dimensions of the shape patterns, it is recommended to apply the second method which requires the proper software to recognize the boundaries or edges differentiating the pattern area from the non-pattern area of the captured image as well as to identify the two-dimensional coordinates of pixels that constitute the image. This document does not specify the software to recognize the edge nor the edge detection algorithm. Depending on the user's concern and purpose, the first method or the second method can be used, or both.

This document excludes the standardization of the measurement system. It specifies the properties related to the shaped patterns of the printed pattern obtained from the optical measurement system.

## 1 Scope

This part of IEC 62899 specifies the measurement methods of the dimensions of the shape patterns in printed electronics. These printed patterns are treated as two-dimensional on a substrate. When the patterns are definitely affected by three-dimensional configurations, these are specified in measurement methods for vertical variance in IEC TR 62899-402-4 in printed electronics.

NOTE The measurement methods of dimensions of the shape patterns considering three-dimensional characteristics can be developed later after the measurement methods for vertical variance are established.

## 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

ISO 187, *Paper, board and pulps - Standard atmosphere for conditioning and testing and procedure for monitoring the atmosphere and conditioning of samples*

ISO 291, *Plastics - Standard atmospheres for conditioning and testing*

## Bibliography

IEC 62899-301-2, *Printed electronics - Part 301-2: Equipment - Contact printing - Rigid master - Measurement method of plate master pattern dimension*

IEC 62899-401, *Printed electronics - Part 401: Printability - Overview*

IEC 62899-402-1, *Printed electronics - Part 402-1: Printability - Measurement of qualities - Pattern width*

IEC 62899-402-2, *Printed electronics - Part 402-2: Printability - Measurement of qualities - Edge waviness*

IEC 62899-402-3, *Printed electronics - Part 402-3: Printability - Measurement of qualities - Voids in printed pattern using a two-dimensional optical image*

IEC TR 62899-402-4, *Printed electronics - Part 402-4: Printability - Measurement of qualities - Classification and measurement methods for morphology*

IEC 62899-403 (all parts), *Printed electronics - Part 403: Printability - Requirements for reproducibility*

IEC 62899-403-1, *Printed electronics - Part 403-1: Printability - Requirements for reproducibility - Basic patterns for evaluation of printing machine*

ISO 19262:2015, *Photography - Archiving Systems - Vocabulary*

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Park, J., Nguyen, H. A. D., Park, S., Lee, J., Kim, B., & Lee, D. (2015). *Roll-to-roll gravure printed silver patterns to guarantee printability and functionality for mass production*. *Current Applied Physics*, 15(3), 367-376.